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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Kinsman et al.

**Serial No.:** 09/917,127

**Filed:** June 27, 2001

**For:** METHOD FOR FABRICATING A CHIP  
SCALE PACKAGE USING WAFER LEVEL  
PROCESSING AND DEVICES RESULTING  
THEREFROM

**Examiner:** Unknown

**Group Art Unit:** 2815

**Attorney Docket No.:** 3572.1US (97-1243.1)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

October 26, 2001  
Date of Deposit

Signature of registered practitioner or other person  
having reasonable basis to expect mailing to occur  
on date of deposit shown pursuant to 37 C.F.R. §  
1.8(a)(1)(ii)

Joseph A. Walkowski  
Typed/printed name of person whose signature is  
contained above

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. The listed documents are from co-pending application Serial No. 09/586,243, filed June 2, 2000. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as

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defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

DOCUMENTS

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Issue Date</u>	<u>Inventor</u>
5,143,865	09/1992	Hideshima et al.
5,908,317	06/1999	Heo
6,054,772	04/2000	Mostafazadeh et al.
6,097,098	08/2000	Ball
6,150,717	11/2000	Wood et al.
6,208,018 B1	03/2001	Ma et al.

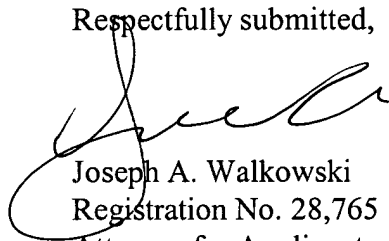
Foreign Patent Documents

<u>Document No.</u>	<u>Date</u>	<u>Country</u>
11-135663	05/1999	Japan
2000-133669 A	05/2000	Japan

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,



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Date: October 26, 2001

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Enclosures: Form PTO-1449  
Copy of documents cited

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